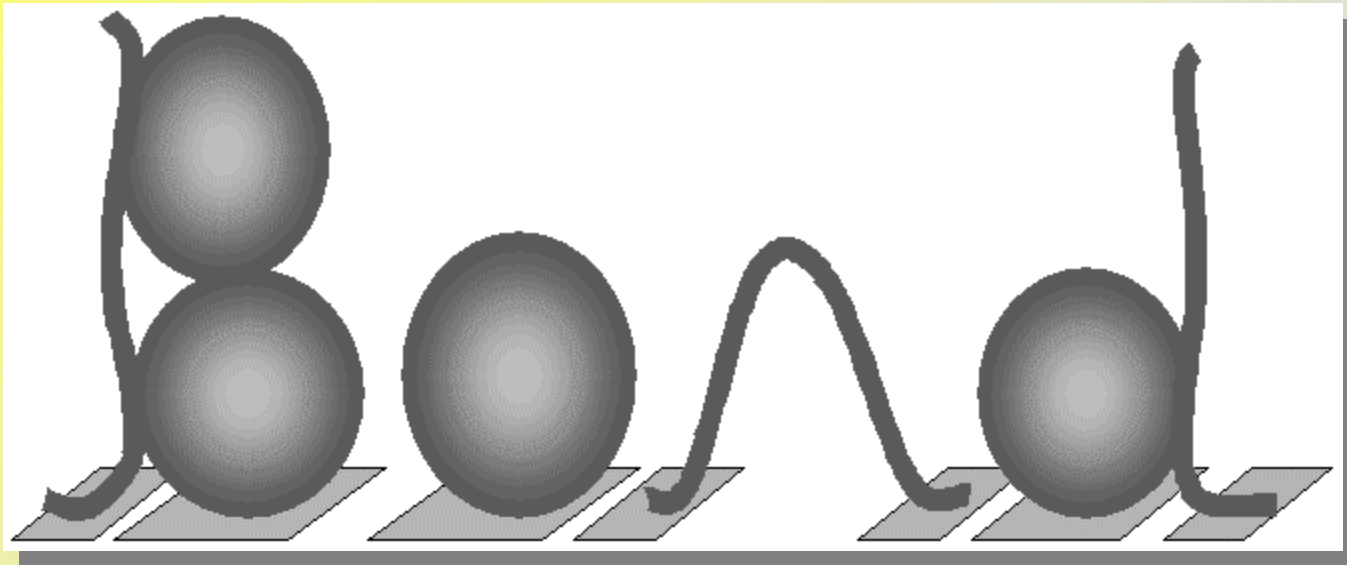


Workshop on Bonding and Die Attach Technologies

CERN, 11 and 12 June 2003



W E L C O M E

Why did we organize this workshop ?

4 LHC experiments

~ 350 m² of Silicon detectors

~ several 10⁴ detector modules

~ several 10⁷ wire bonded connections

~ several 10⁷ bump bonded connections

Detectors have to operate for ~10 years in harsh radiation environment (+2-5 years storage before), at modulated temperature.

Detectors are fabricated by a world wide distributed network of labs/industries → lots of manipulations, packing, unpacking, transports, inspections

Bonding and glueing are generally considered as mature industrial interconnect technologies. The question of bondability and reliability of the bond is usually addressed very late in the production cycle.

This workshop should

... provide a technical overview of the available bonding and die attach technologies.

Unfortunately we were not able to organize a talk on TAB bonding, nor did we find a speaker for an overview talk on die attach technologies

... raise awareness of the different parameters and phenomena which influence the quality and long term reliability of bonded connections

... provide a forum for the exchange of experience, problems and solutions

... Allow for an information exchange between industry (machine manufacturers) and users

This is a WORKSHOP and not a conference.

Agenda leaves ample time for discussions after talks. Don't hesitate to ask your questions!

In addition we have a special discussion session this evening (what you always wanted to know, but never dared to ask...)

Workshop organisation

All sessions take place here in this room (40-SS-C01)

Coffee breaks in the cafeteria (ground floor) in this building.

All people wearing the 'bond' badge get free coffee/tea & croissant in the morning and coffee/tea in the afternoon.

Workshop dinner: tonight 20:00 in the restaurant Bois Joly/Crozet (F).
35 Euros/54 CHF.

Those who are registered, please pay during today's coffee breaks.

Departure for the dinner: 19:45 in front of B 39. Bring your car! Don't forget your passport!

Tomorrow, 16:00. Two guided tours. ~10 people/tour.
Meeting point in front of B 40.

1. Printed Circuit Lab. Rui de Oliveira (3 minutes walk from B40)
2. EP Divisional Silicon Facility + Bond Lab. Ian McGill (10 minutes walk from B40)